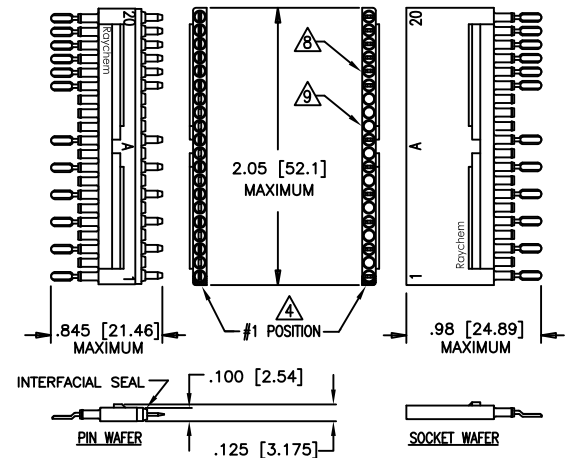
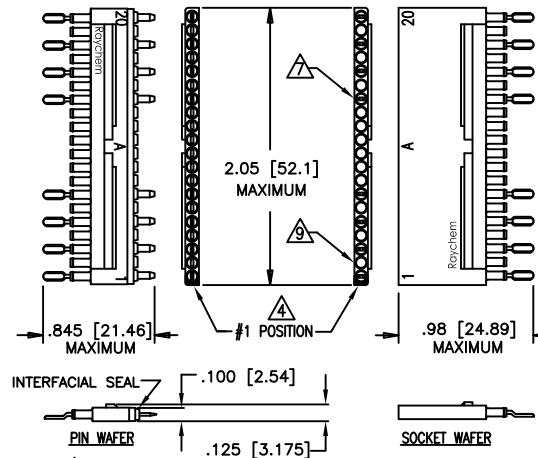
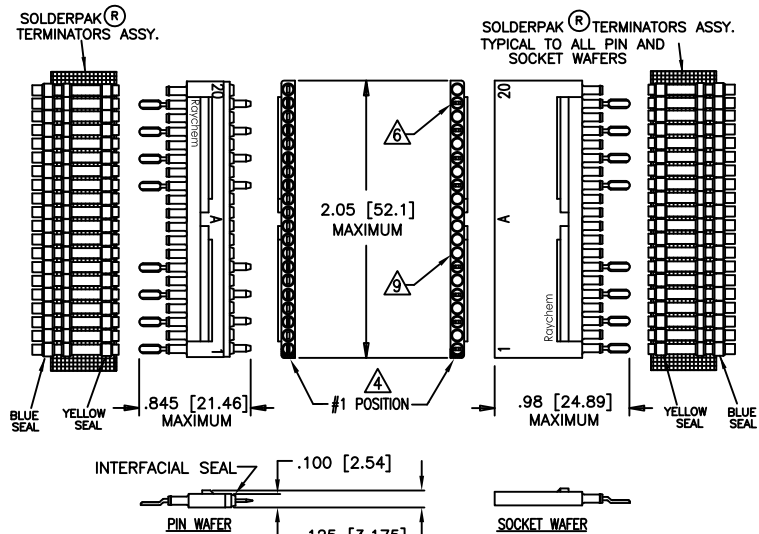


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REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	PER ECO-10-015431	JULY/27/2010	M. HIGGY
B	PER ECO-11-003194	Feb/14/2011	M. HIGGY
B1	PER ECO-11-004231, Administrative change	Feb/25/2011	M. HIGGY



THIS MODEL HAS 8 ACTIVE CONNECTIONS, (VERSION 2)
 LINE 2, 4, 6, 8, 9, 10, 11, 12, 13, 15, 17
 AND 19 CONNECTIONS DO NOT EXIST.

THIS MODEL HAS 12 ACTIVE CONNECTIONS.
 LINE 2, 4, 6, 8, 10, 12, 13 AND 14
 CONNECTIONS DO NOT EXIST.

FIGURE II

FIGURE III

NOTES: 1. PART NUMBER VARIABLE: SEE TABLE I.

2. MATERIAL:
- A) PIN/SOCKET WAFER HIGH GRADE POLYARYLENE THERMOPLASTIC.
 - B) PIN CONTACT COPPER ALLOY PER ASTM B36, ASTM B36M
 - C) SOCKET CONTACT COPPER ALLOY PER ASTM B103, ASTM B103M (A).
 - D) INTERFACIAL SEAL FLUOROSILICONE PER MIL-R-25988.
 - E) SOLDERPAK TERMINATORS ASSY. REFER TO TYCO ELECTRONICS DRAWING CTA-0036.
3. FINISH:
- A) PIN/SOCKET WAFER AS MOLDED.
 - B) PIN/SOCKET CONTACT ENGAGING END GOLD PLATE PER ASTM B488, CLASS 1, TYPE 2, GRADE C.
 - C) CONTACT TAIL SOLDER COATED PER IPC J-STD 006 (Sn63).
4. NUMBER ONE POSITION IS MARKED AS SHOWN IN CONTRASTING COLOR ON INTERFACE.

5. THIS PRODUCT IS QUALIFIED TO SPACE SYSTEM LORAL'S SPECIFICATION 010554 Rev. 21, (PER MIL-DTL-83513 AND TYCO ELECTRONICS SPECIFICATION C-6111 AS APPLICABLE). SEE ISTR-1105 FOR MORE INFORMATION.

6. SEE FIGURE I

7. SEE FIGURE II

8. SEE FIGURE III

9. ALL UNUSED CAVITIES ON SOCKET WAFERS ARE FOR VENTING (OPEN).

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CUSTOMER DRAWING

FIGURE	TABLE I		
	PART#	DESCRIPTION	WEIGHT MAX. GRAMS
I	MTC100-JA2-P11M1	A WAFER, PIN	T.D.
	MTC100-JA2-S11M1	A WAFER, SOCKET	T.D.
II	MTC100-JA2-P11M2	A WAFER, PIN	T.D.
	MTC100-JA2-S11M2	A WAFER, SOCKET	T.D.
III	MTC100-JA2-P11M3	A WAFER, PIN	T.D.
	MTC100-JA2-S11M3	A WAFER, SOCKET	T.D.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. METRIC DIMENSIONS ARE IN BRACKETS.	DRAWN	Zsofia O.	July/19/2010		Raychem Interconnect 300 Condit/Bon Drive Menlo Park, CA 94025 U.S.A.
	CHECKED				
DECIMALS .XXX ± .005 .XX ±	APPROVED			TITLE A WAFER 2 INCH, PIN AND SOCKET FOR ROUND WIRE TERMINATION 20-26 AWG 125 CELSIUS DEGREE OPERATING TEMPERATURE MTC100 SERIES-MODIFIED 3 VARIATION CONTACTS MODELS	SIZE A
	APPROVED	M.HIGGY.	July/19/2010		
ANGLES .X ±	CAD NAME	MTC100-JA2-X11MX		DWG. NO. MTC100-JA2-X11MX	REV B1
WEIGHT: MAXIMUM SEE TABULATION	THIRD ANGLE PROJECTION			SCALE: NONE	SHEET 1 OF 1

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FIGURE I

DRAWING MTC100-JA2-X11MX SHEET 1